

**20088-S2X**

鍍層厚度:

Blank	: 1u"
2	: 15u"
3	: 30u"

**SPECIFICATIONS**

**Electrical:**

1. Current Rating: 5.0A(for VBUS),0.25A(for other)
2. Voltage Rating: 20V
3. Contact Resistance: 40 mΩ Max
4. Insulation Resistance: 100MΩ Min
5. Dielectric Withstanding Voltage: 100V AC

**Mechanical:**

1. Connector Mate and Unmate Force
  - 1.1 Mate force: 2.0 Kgf Max
  - 1.2 Unmate force: 0.8 Kgf Min

**Material:**

1. Housing: LCP, UL 94V-0
2. Contact: Phosphor Bronze
3. Shell: SUS

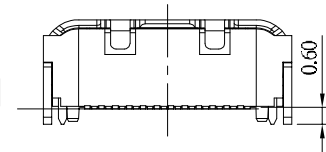
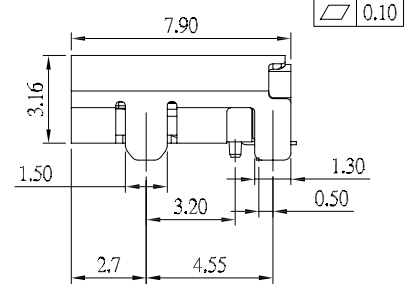
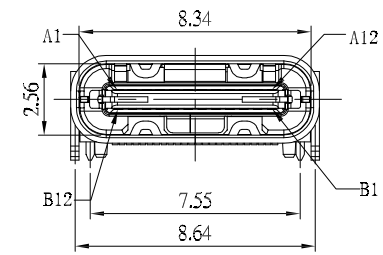
**Finish:**

1. Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
2. Shell: Nickel under Plated surface layer

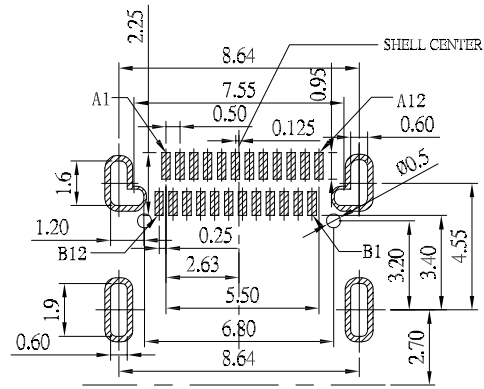
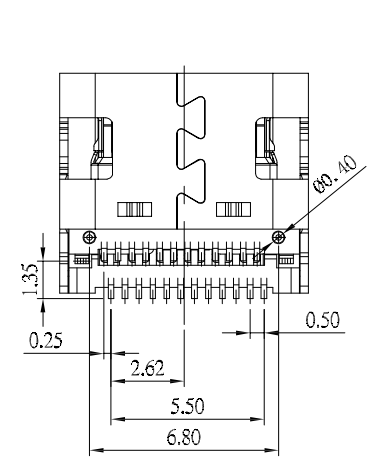


A  
B  
C  
D  
E

A  
B  
C  
D  
E



A1	GND	B12	GND
A2	SSTXP1	B11	SSRXP1
A3	SSTXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	DP1	B7	DN2
A7	DN1	B6	DP2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSTXN2
A11	SSRXP2	B2	SSTXP2
A12	GND	B1	GND
PIN	SIGNAL NAME	PIN	SIGNAL NAME



P.C.B LAYOUT MOUNTING PATTERN

尚益科技有限公司  
JMSCONN TECHNOLOGY CO., LTD.

PROJ		SCALE : F DO NOT SCALE DWG	MOLD NO 20088-S2	REV. X1
APP			MODEL	FILE NO
CHK			UNIT	SHT 1 OF 1
DGN			MM	SIZE A4
DRW	HSIEH	2016.11.10		